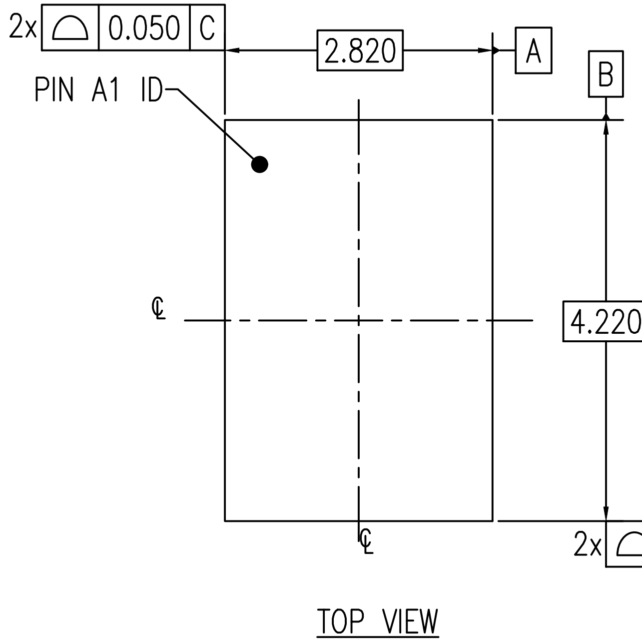
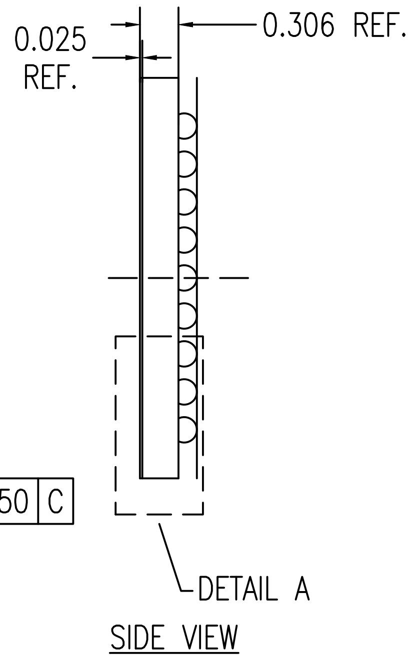
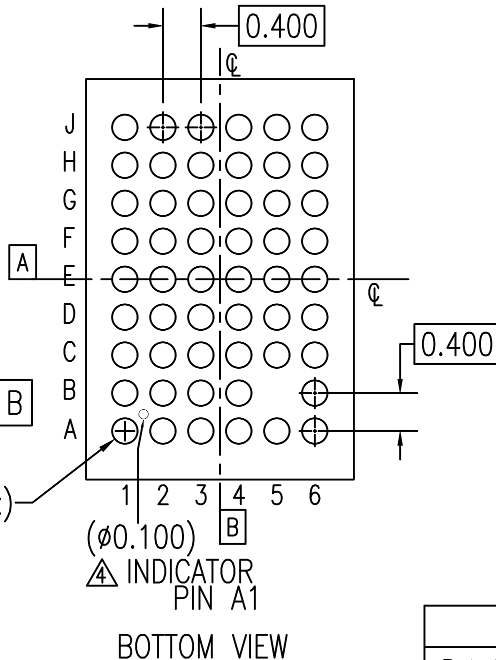
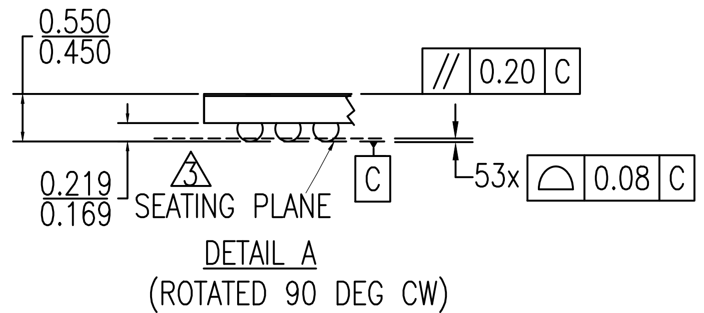
NOTES:
1. ALL DIMENSIONS AND TOLERANCES ARE PER ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. (△) SEATING PLANE AND PRIMARY DATUM -C- ARE DEFINED BY THE CONTACT POINTS OF THREE OR MORE SOLDER BALLS THAT SUPPORT THE DEVICE WHEN PLACED ON A TOP OF A PLANAR SURFACE.
4. (△) BOTTOM PIN#1 INDICATOR OPTIONAL.
5. BALL SIZE BEFORE REFLOW IS 0.25MM.
6. WAFER SCRIBE LINE WIDTH 90UM; KERF WIDTH 40UM.









Package Revision History		
Date Created	Rev No.	Description
April 1, 2019	Rev 00	Initial Release

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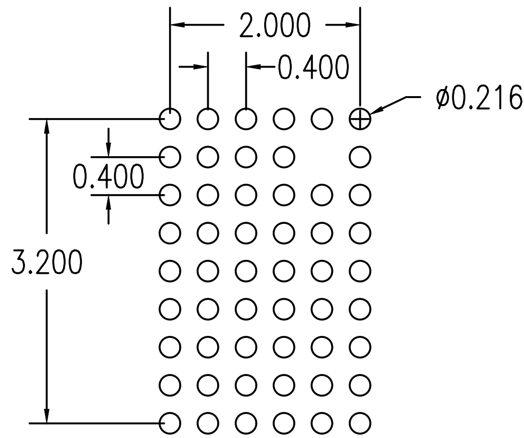

RECOMMENDED LAND PATTERN DIMENSION

NOTE:
1. ALL DIMENSIONS ARE IN MM, ANGLES IN DEGREES.
2. TOP DOWN VIEW, AS VIEW ON PCB.
3. NSMD LAND PATTERN ASSUMED.
4. LAND PATTERN RECOMMENDATION AS PER IDT DSBGA APPLICATION NOTE.

	Package Revision History	
Date Created	Rev No.	Description
May 6, 2019	Rev 01.	Change Package Code from AZQ53 To AWQ53
April 1, 2019	Rev 00	Initial Release

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